

# The FERMI@Elettra MPS



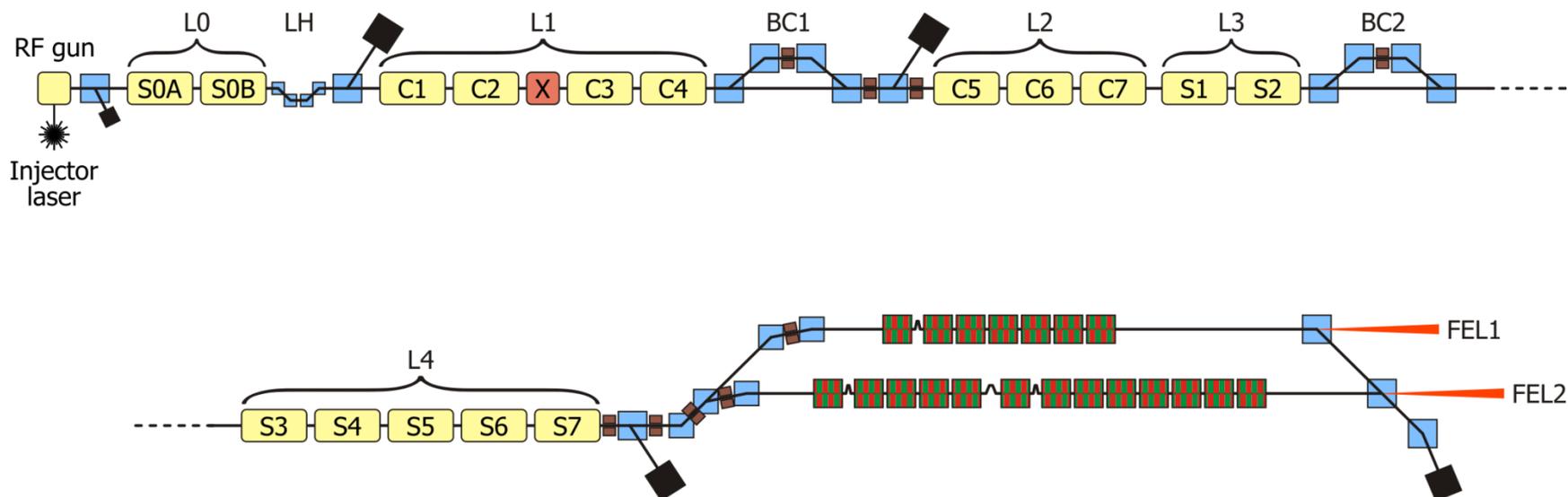
L. Fröhlich, A. I. Bogani, K. Casarin, G. Cautero, G. Gaio,  
 F. Giacuzzo, D. Giuressi, A. Gubertini, R. H. Menk, E. Quai,  
 G. Scalamera, A. Vascotto (Sincrotrone Trieste, Basovizza, Italy)  
 L. Catani (INFN, Rome, Italy), D. Di Giovenale

- FERMI@Elettra
- MPS architecture
- General features
  
- Subsystems:
  - Ionization chamber BLMs
  - RADFET online dosimetry

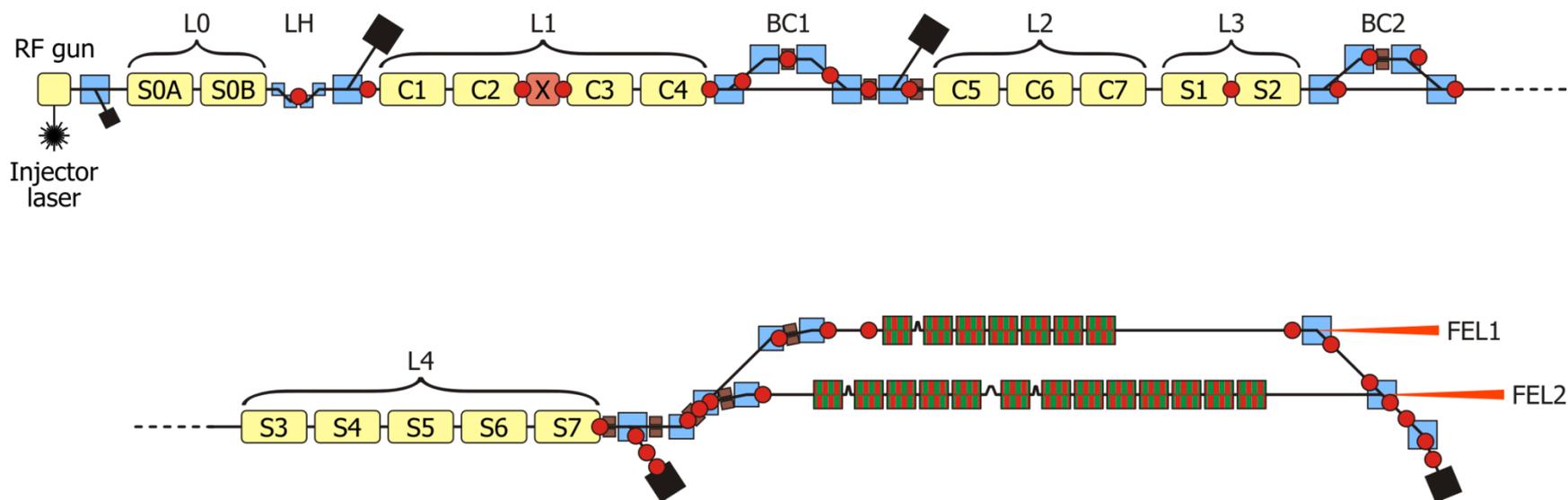


Map:  
Wikimedia Commons



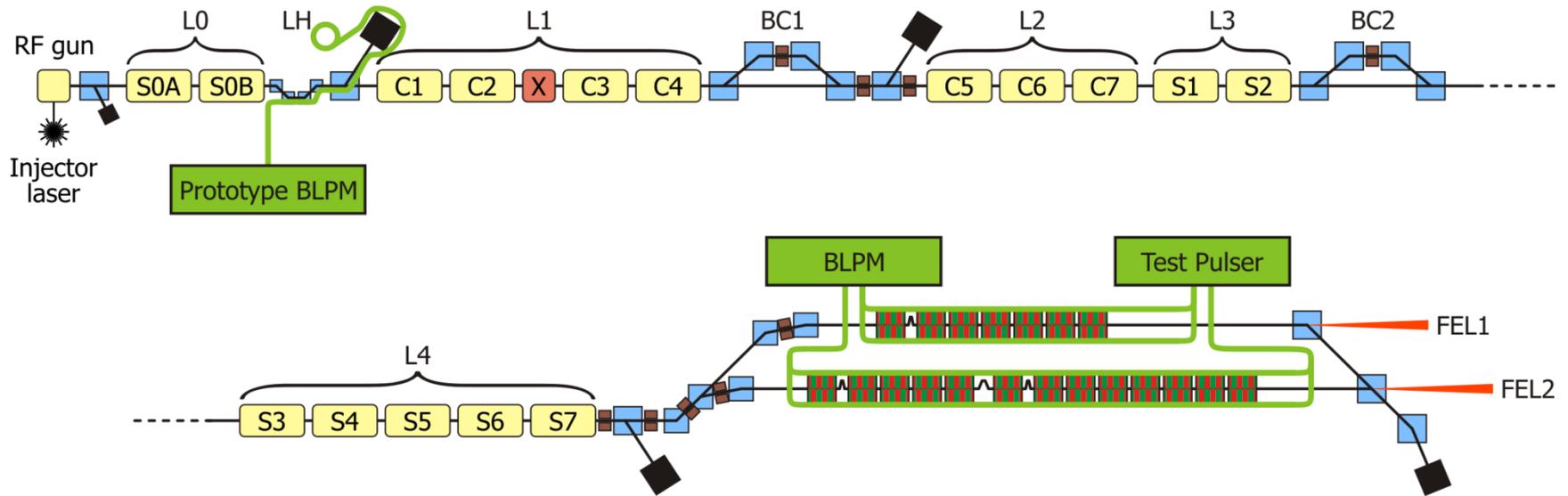


	<b>Energy</b>	<b>Bunch Charge</b>	<b>Repetition Rate</b>	<b>Beam Power</b>
Typical	1.2 GeV	350 pC	10 Hz	4.2 W
Design	1.5 GeV	1 nC	50 Hz	75 W

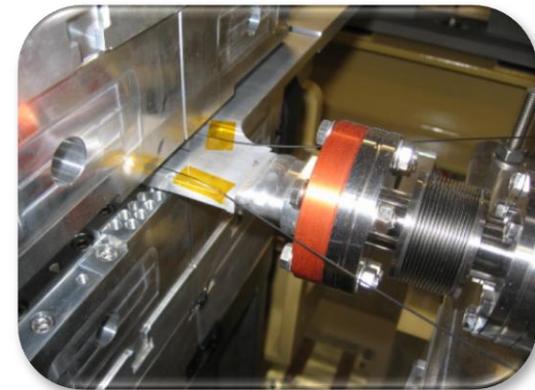


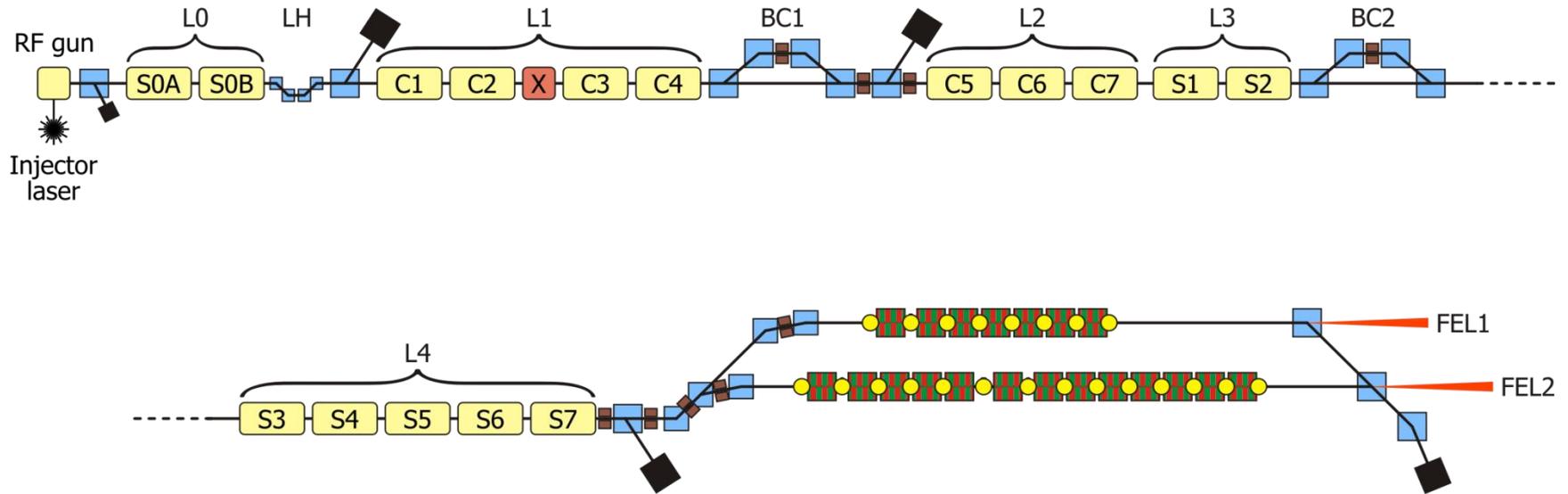
## PIN diode BLMs

K. Casarin, E. Quai,  
S. Sbarra, A. Vascotto

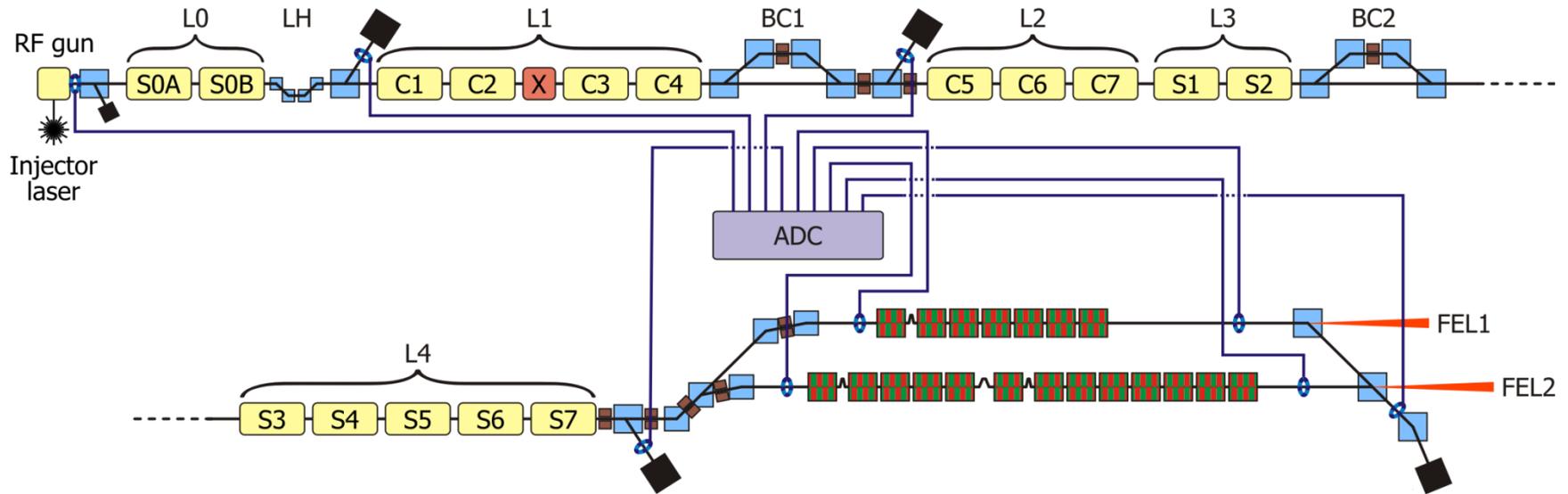


## Cherenkov Fiber Beam Loss Position Monitors (BLPMs)

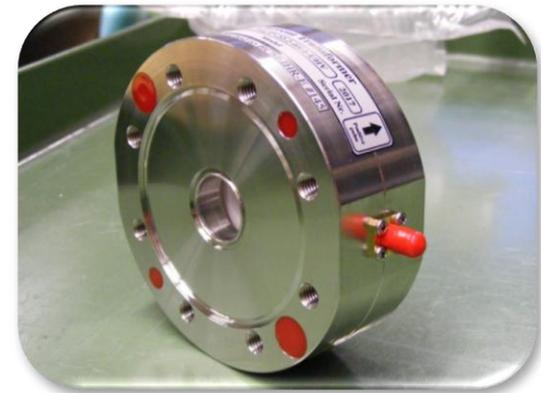




## Ionization Chamber Beam Loss Monitors (BLMs)

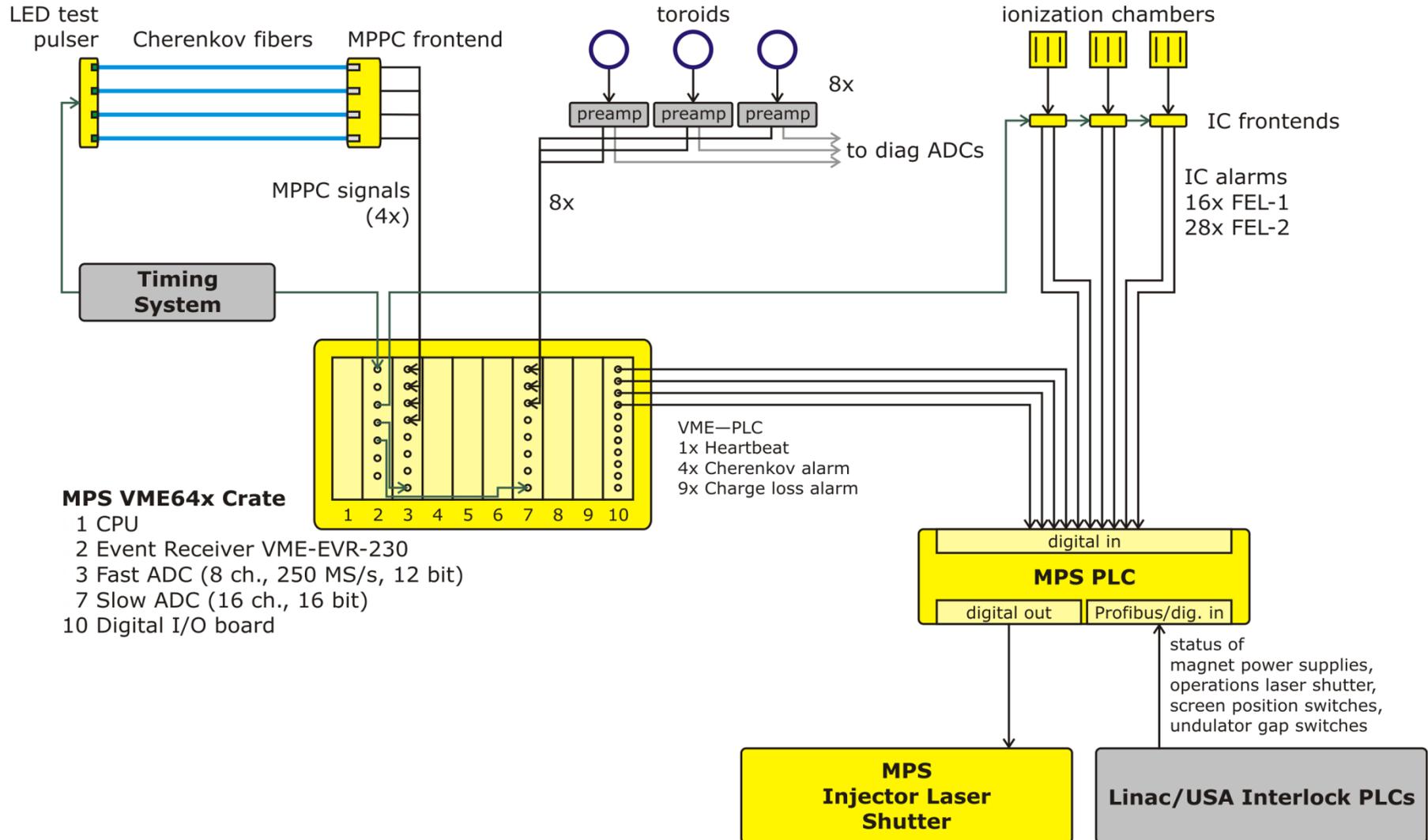


## Charge Monitors



S. Bassanese

# MPS Architecture & General Features

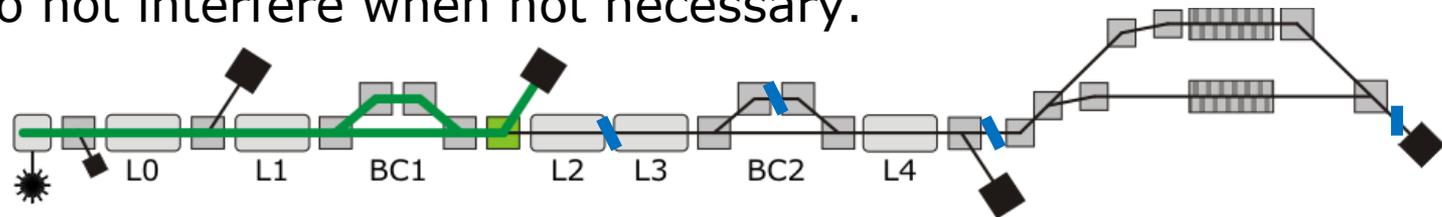


## Screen Interlock

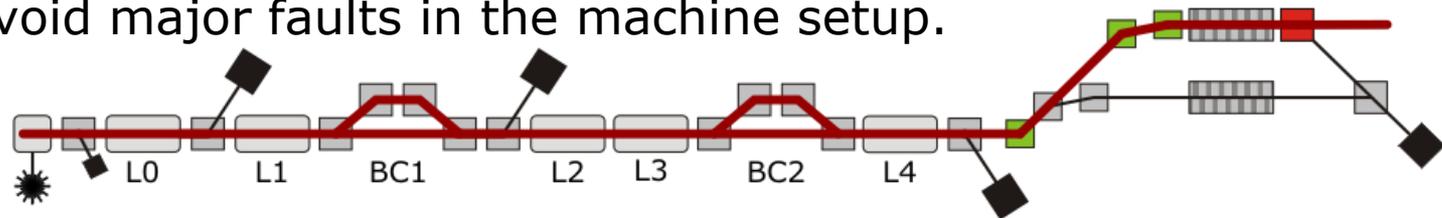
- Inhibits electron beam when:
  - Screens moving or in undefined/forbidden position
  - Linac screen inserted when in FEL-1 or FEL-2 mode
- Only active for screens in current beam path

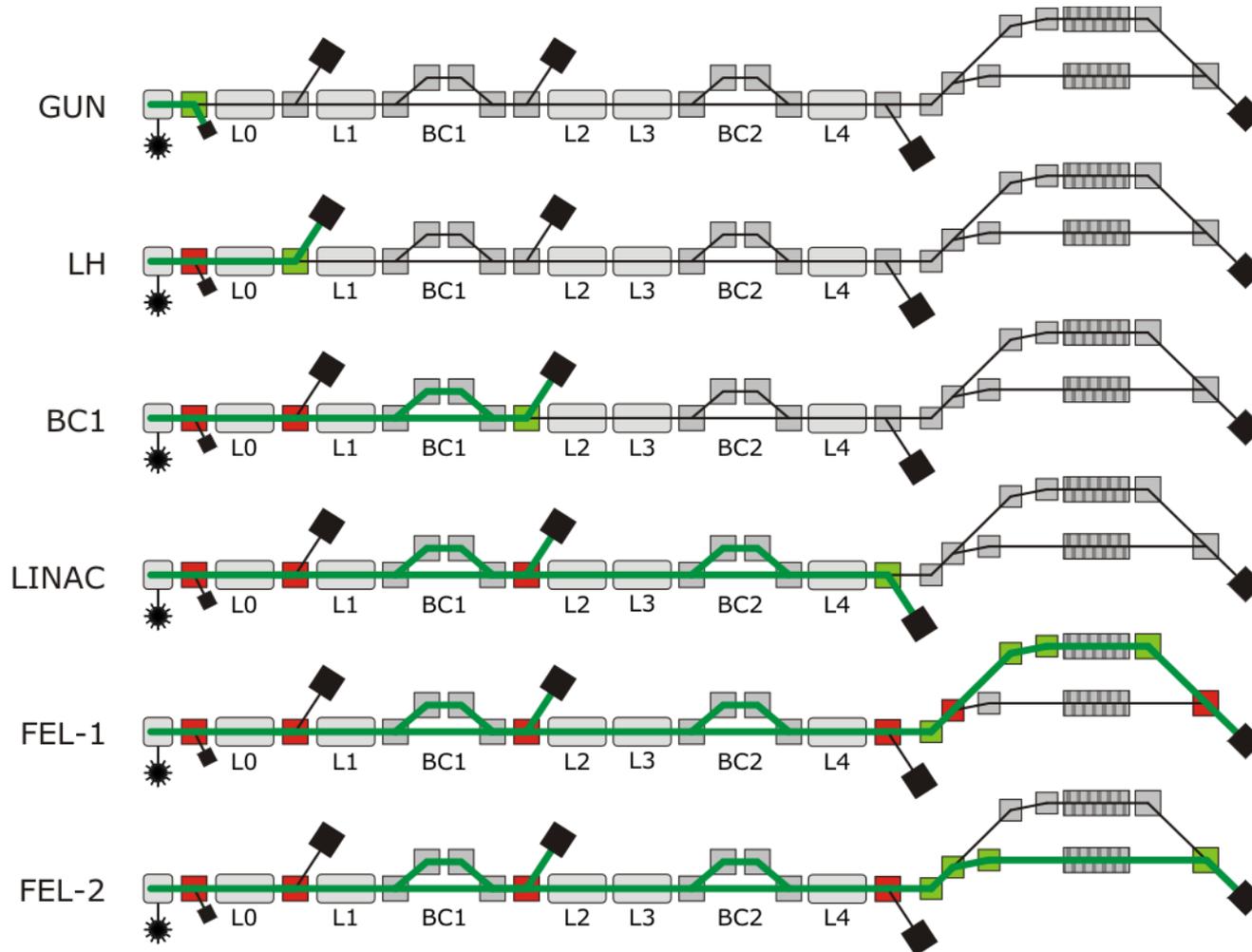
## Operation Mode

Purpose 1: Do not interfere when not necessary.

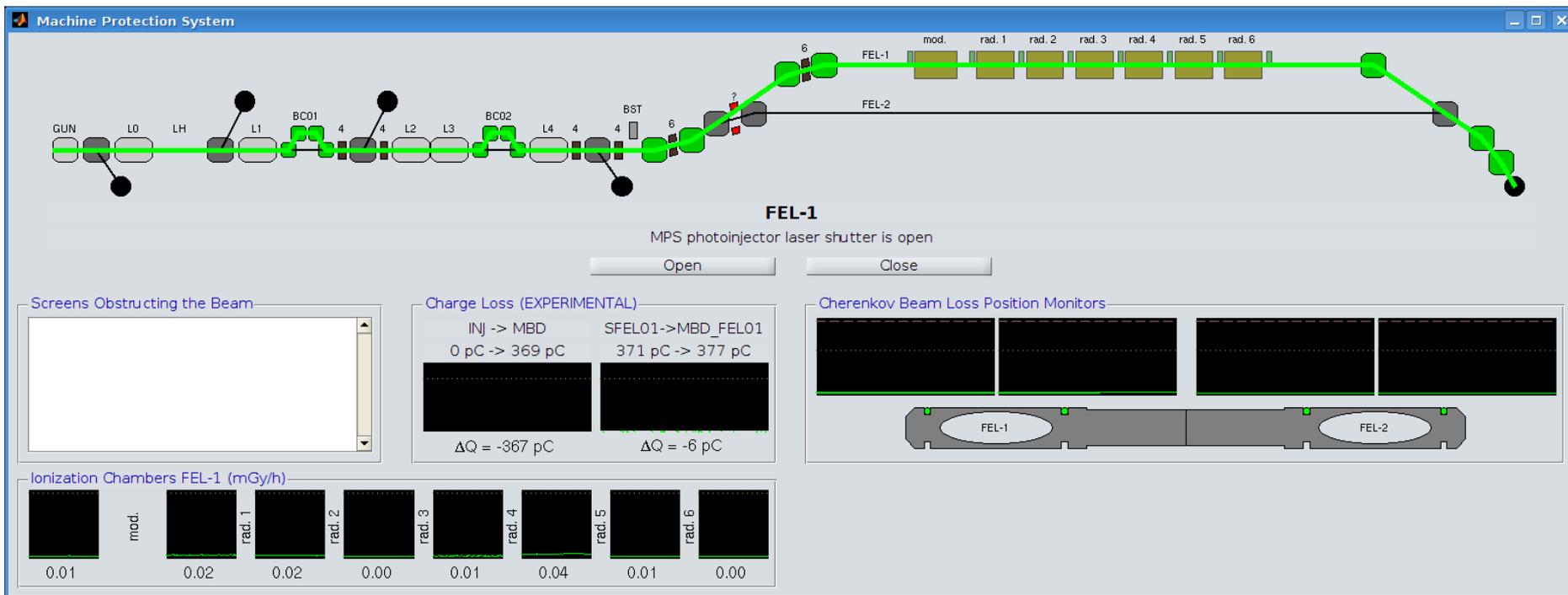


Purpose 2: Avoid major faults in the machine setup.





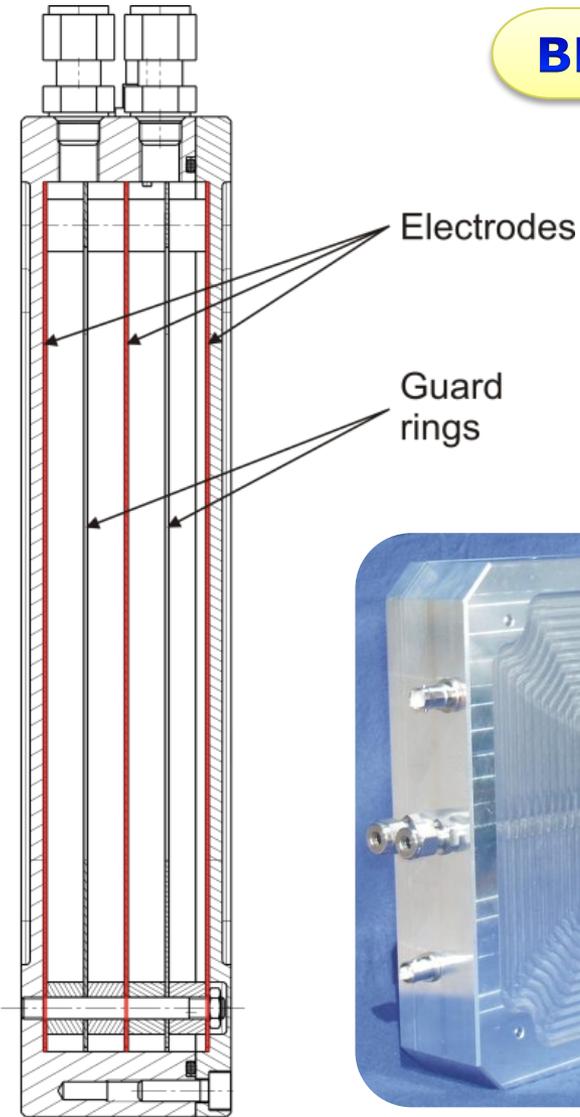
Dipole currents monitored via DCCT and analog PLC input.

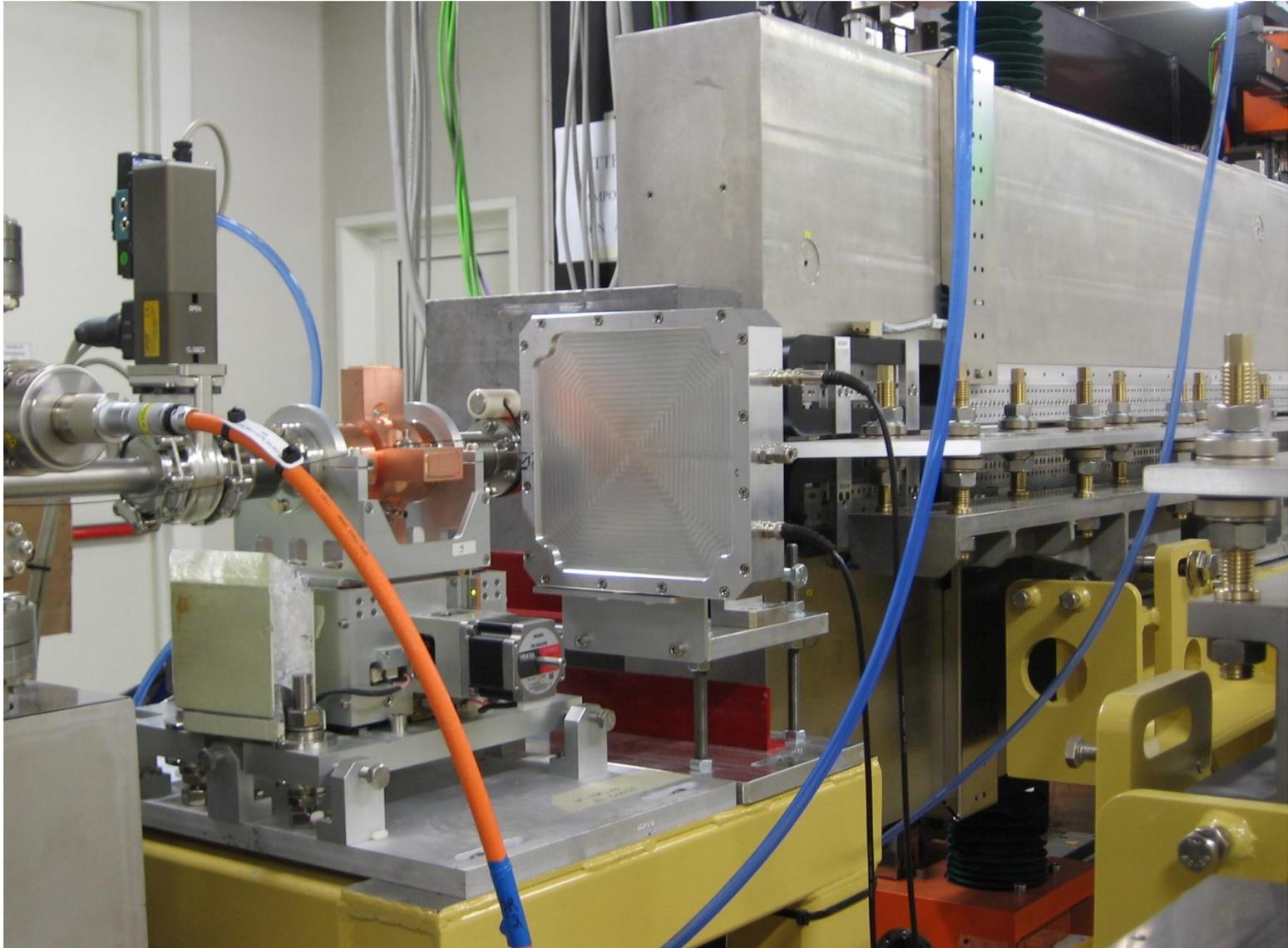


# Ionization Chambers

- Milled aluminum enclosure
- Electrodes: printed circuit boards
- Use in air or with gas flux
- Volume:  
1.3 l
- Voltage:  
up to 1000 V
- Sensitivity (air):  
 $\sim 46 \mu\text{C}/\text{Gy}$
- Leakage current:  
 $\ll 200 \text{ fA}$  (at 1000 V)
- Fermi:  
1 ionization chamber in air  
per undulator segment (19 total)

**BLM-IC02**





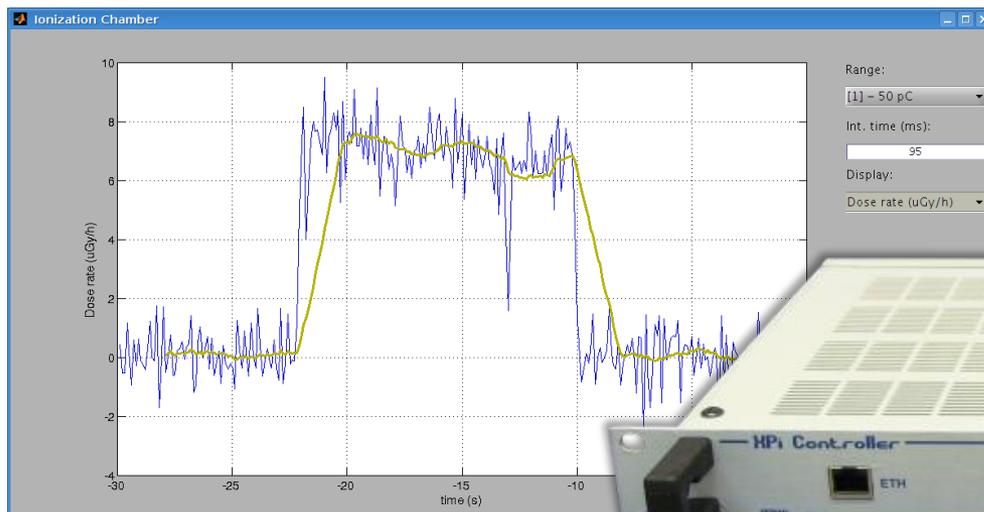
- 19" XPi modular data acquisition system
- Microprocessor controlled
- Ethernet interface
- 1× HV generation up to 2000 V (power  $\leq 1$  W)
- 4× Charge-integrating amplifier and 20-bit ADC

**XPi DAS**

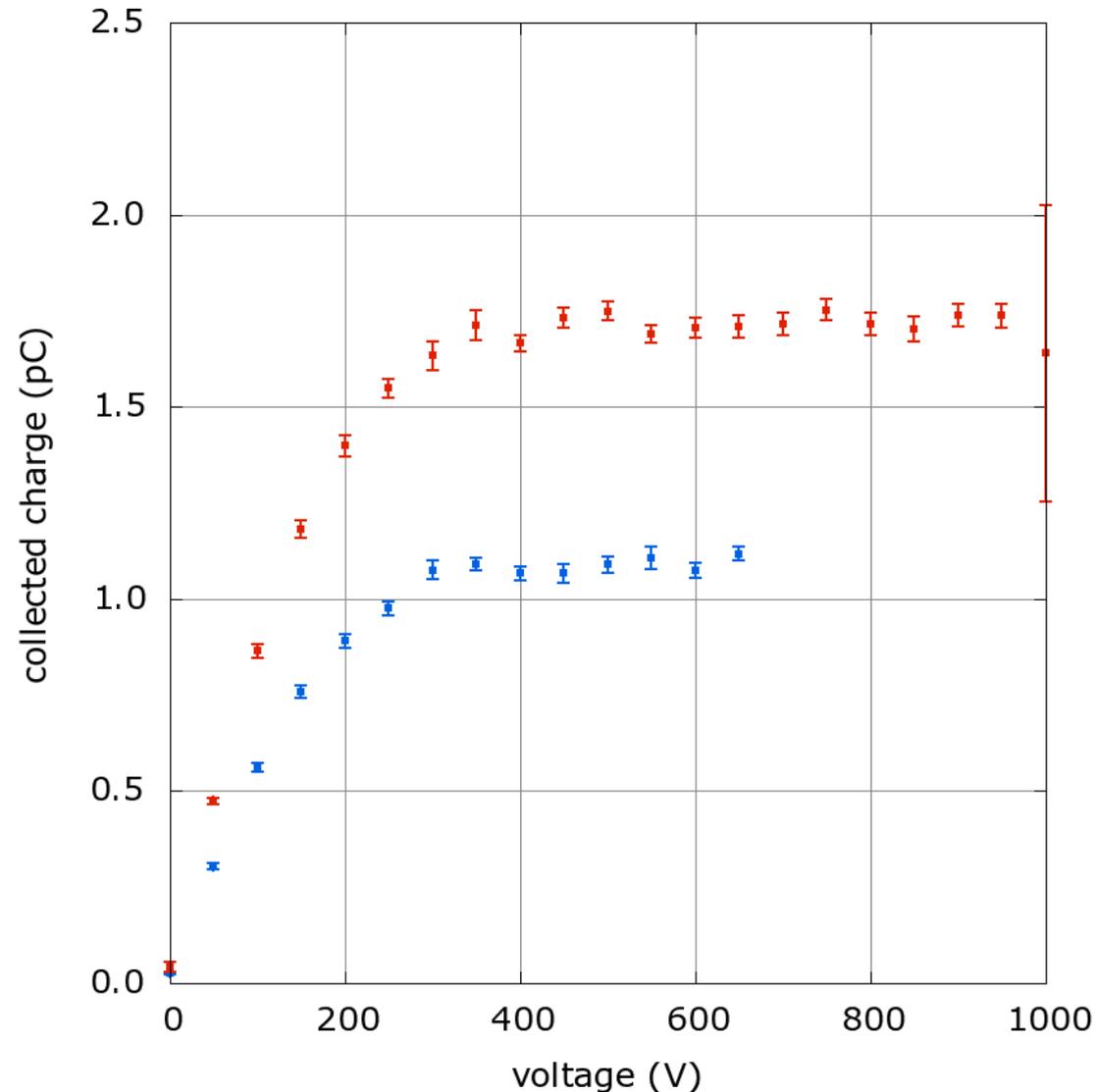


**XPi DAS**

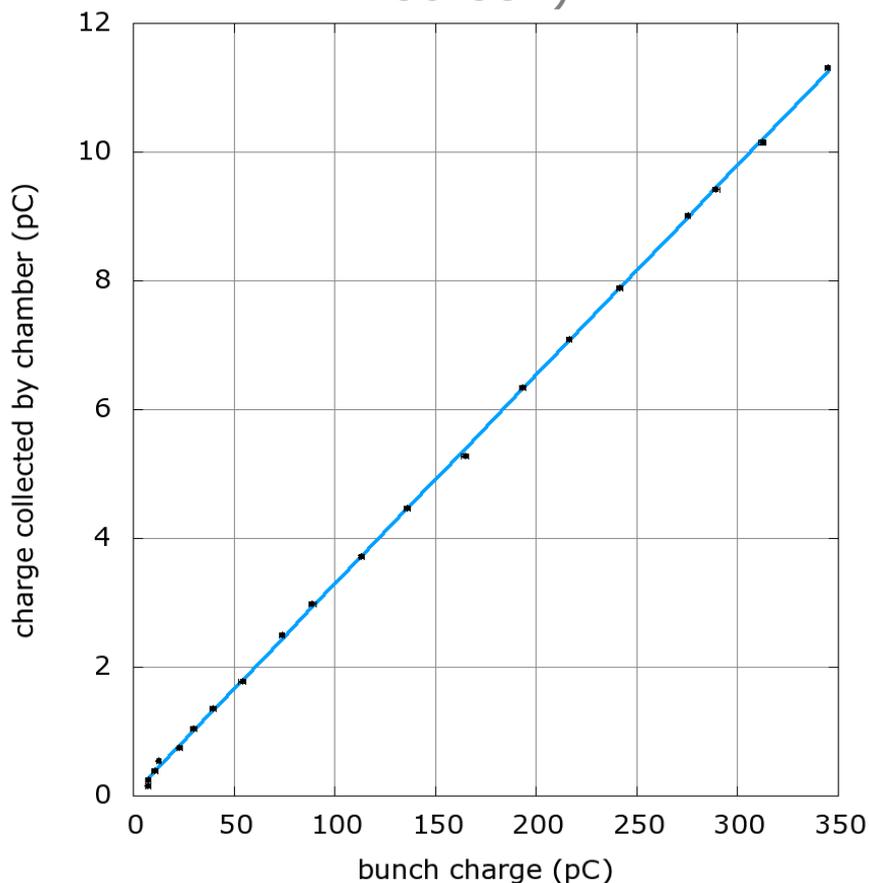
- Full charge range:  
0...50 pC — 0...1.8 nC
  - Integration time: 1 ms – 1 s
  - 2 programmable alarm outputs
  - Noise floor (with Fermi chamber):  
<0.4  $\mu\text{Gy/h}$  (rms)
- Tango server
  - Data acquisition tested up to 50 Hz



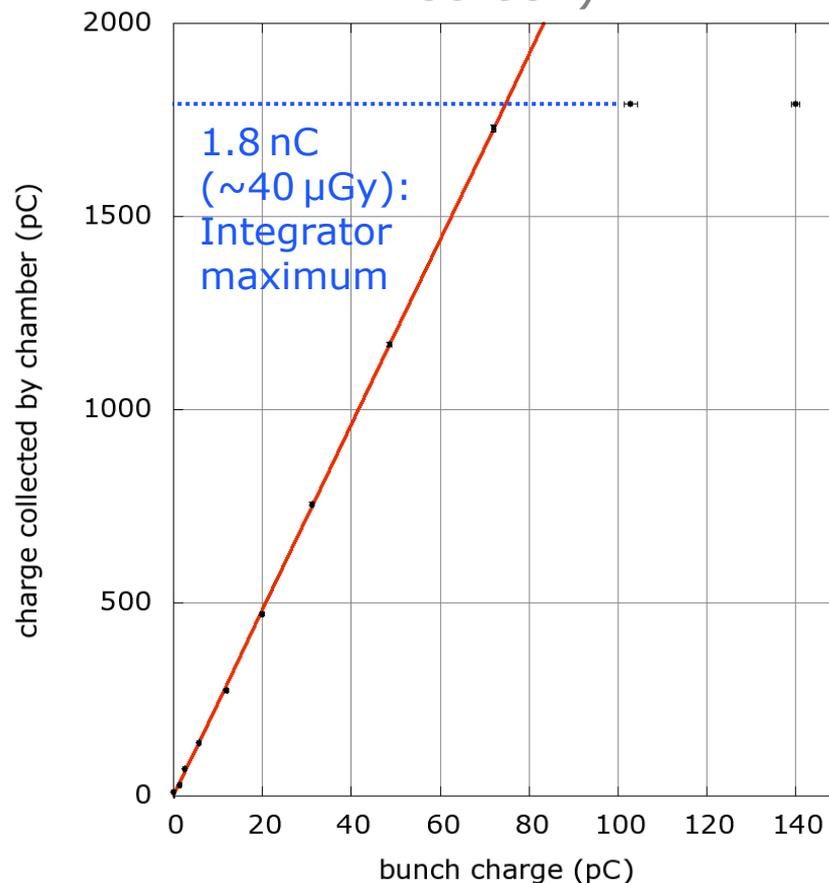
- Air filled chamber
- Charges collected:
  - Electrons
  - Oxygen ions ( $O_2^-$ )
  - Positive ions ( $N_2^+$  etc.)
- Integration time: 3 ms (2 ms sufficient to collect all charges)



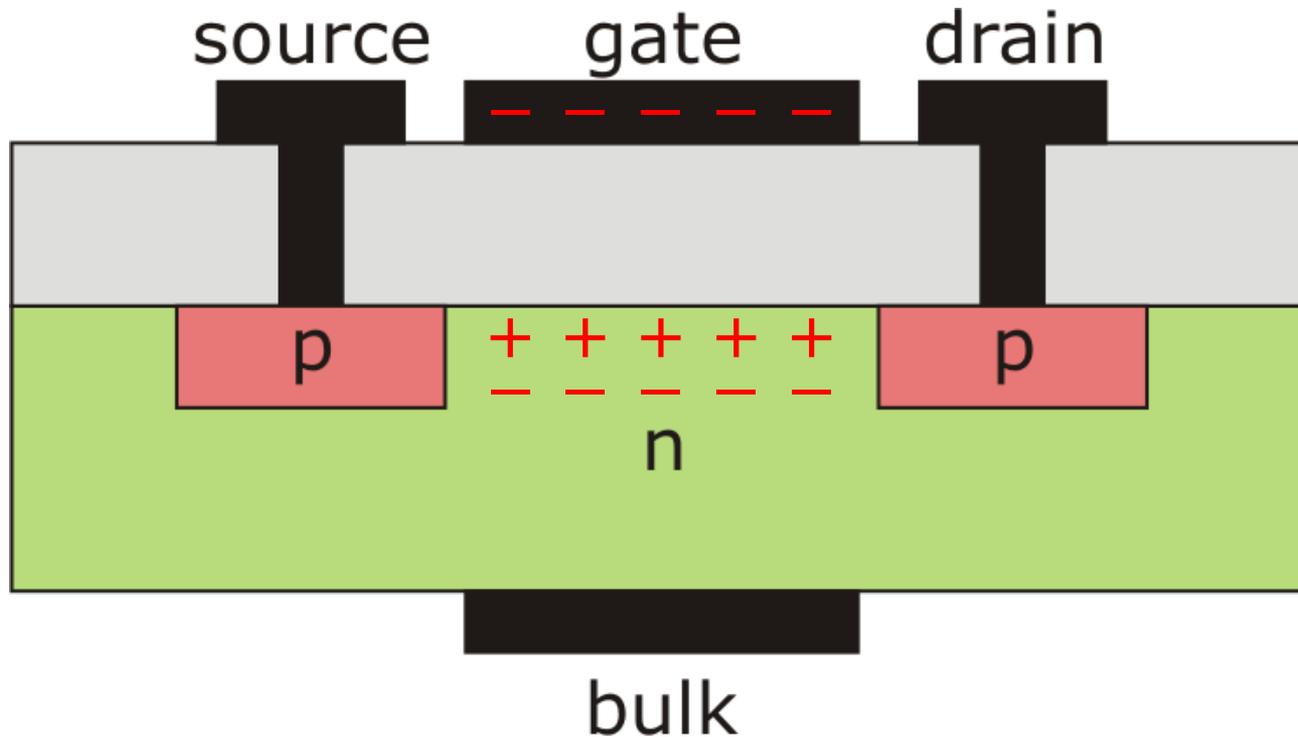
Low dose rates  
( $\sim 20$  cm downstream of screen)



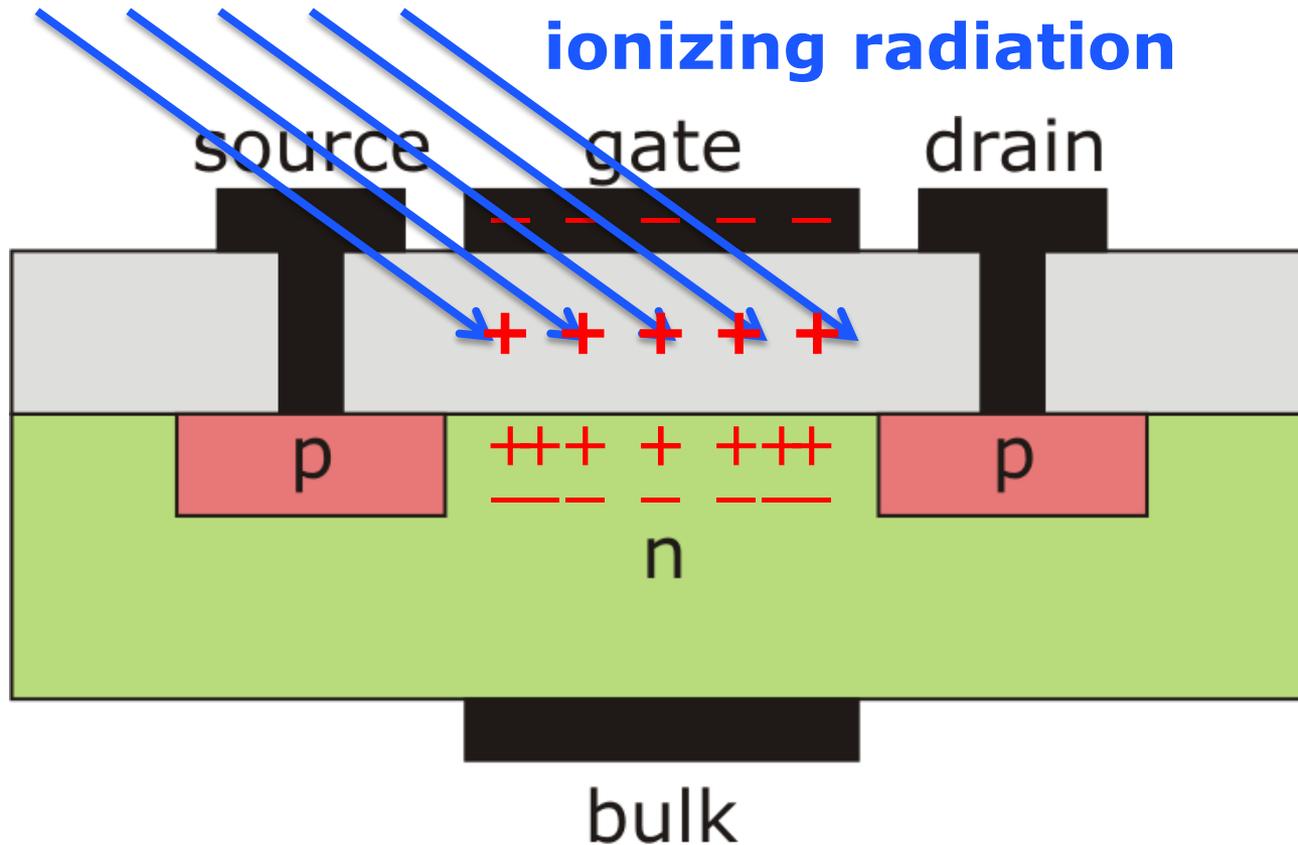
High dose rates  
( $\sim 4$  m downstream of screen)



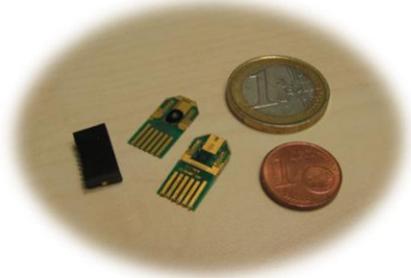
# Online Solid-State Dosimetry



negative gate potential  $\rightarrow$  conductive inversion layer

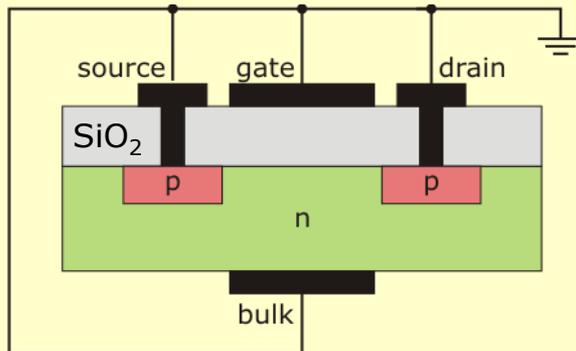


ionizing radiation → stationary charges in insulation layer

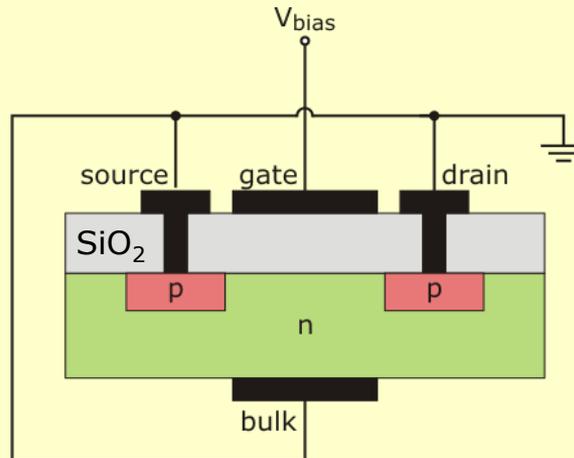


- REM Oxford Ltd. RADFET RFT-300-CC10G1
- Chip contains 2 p-channel MOSFETs with 300 nm insulator layer

exposure  
"zero bias"



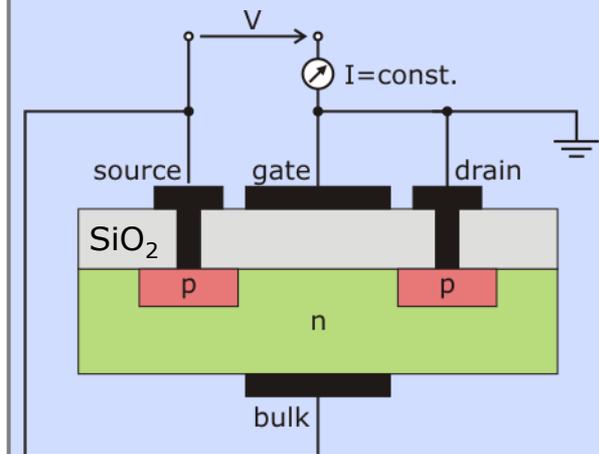
exposure  
with bias voltage



$V_{\text{bias}} > 0$ : more sensitive

$V_{\text{bias}} < 0$ : more linear

read-out



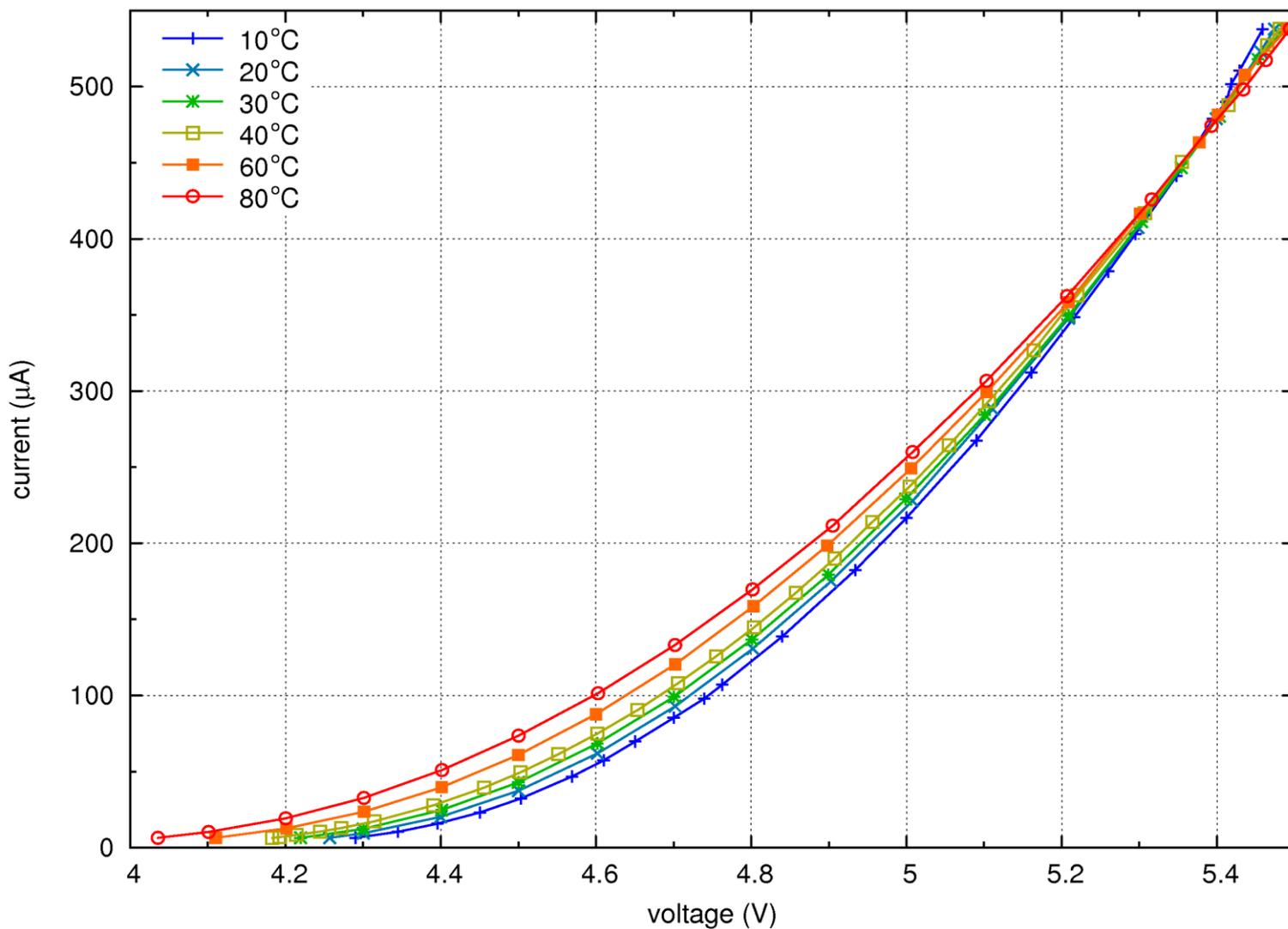
Track voltage for constant current (490  $\mu\text{A}$ ) between source and drain

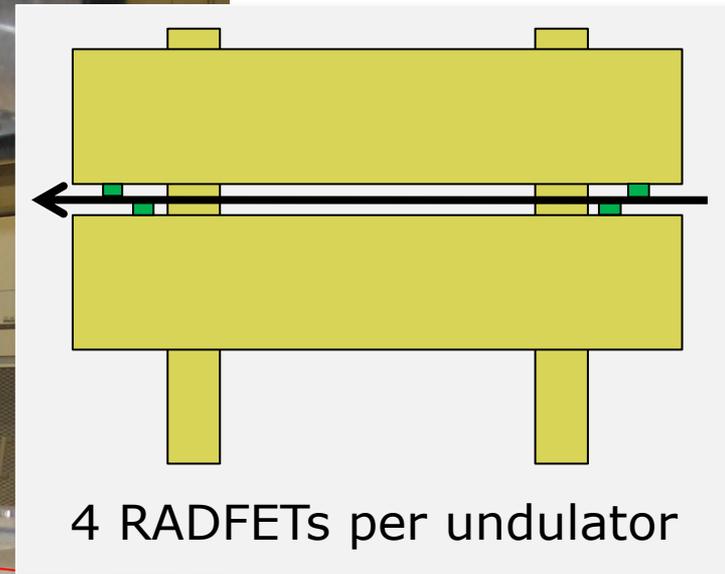
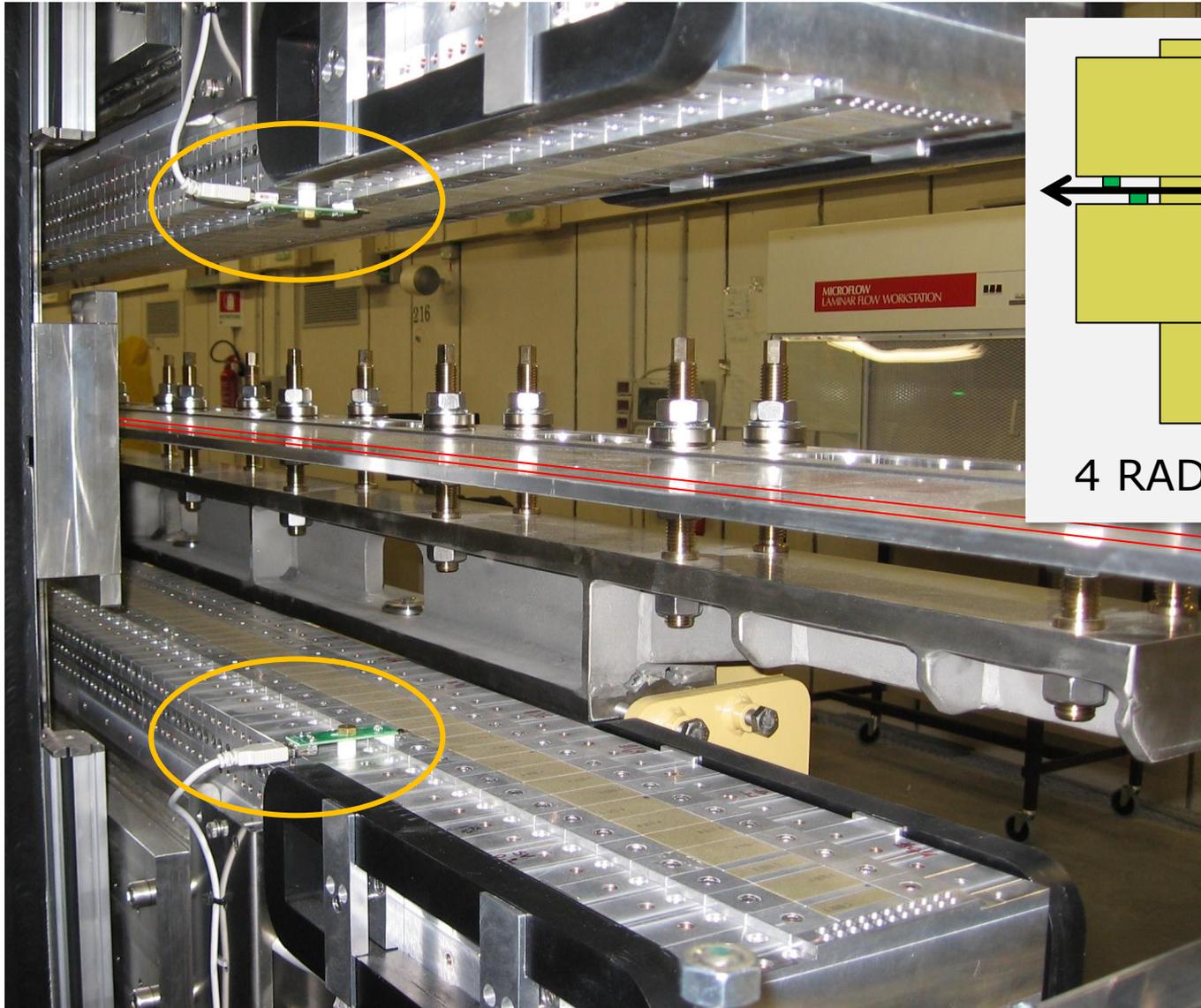
- Microprocessor controlled
- Ethernet connection
- 4 RADFET channels
- Fixed read-out current: 490  $\mu\text{A}$
- Voltage read-out: 24 bit ADC, up to 25 V
- Programmable interlock output
- Uses standard USB cables

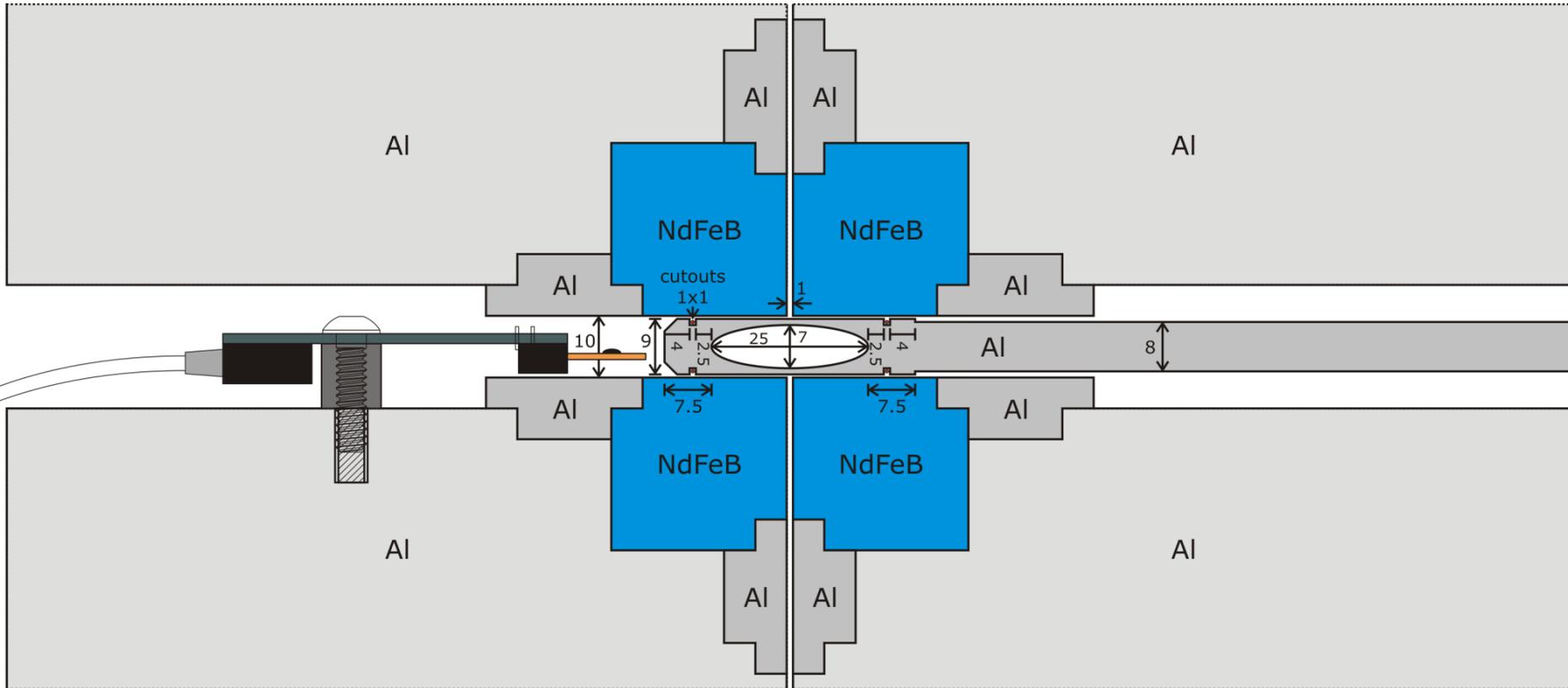
**L01-DOSFET**



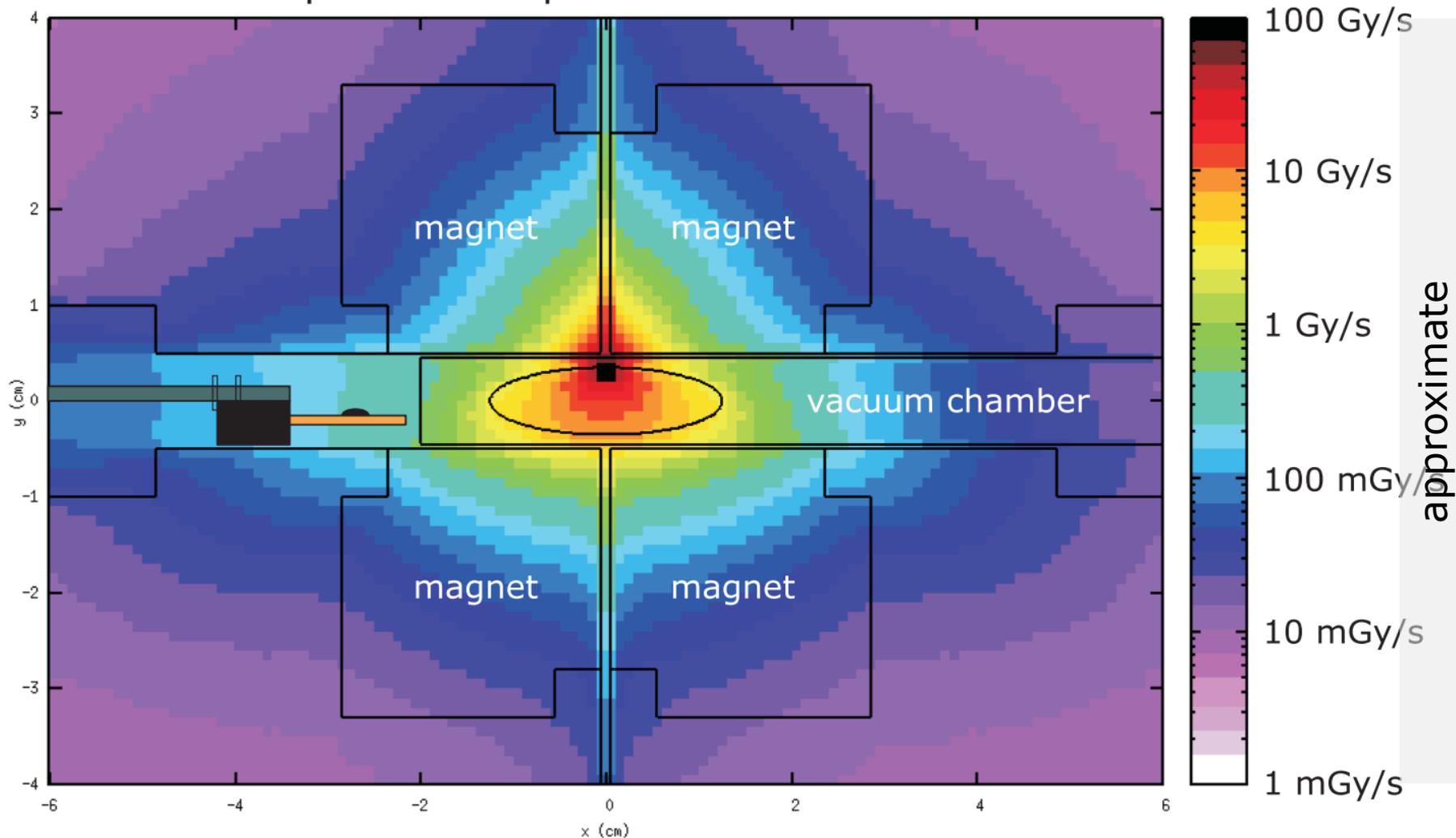
Photo: M. Peloi



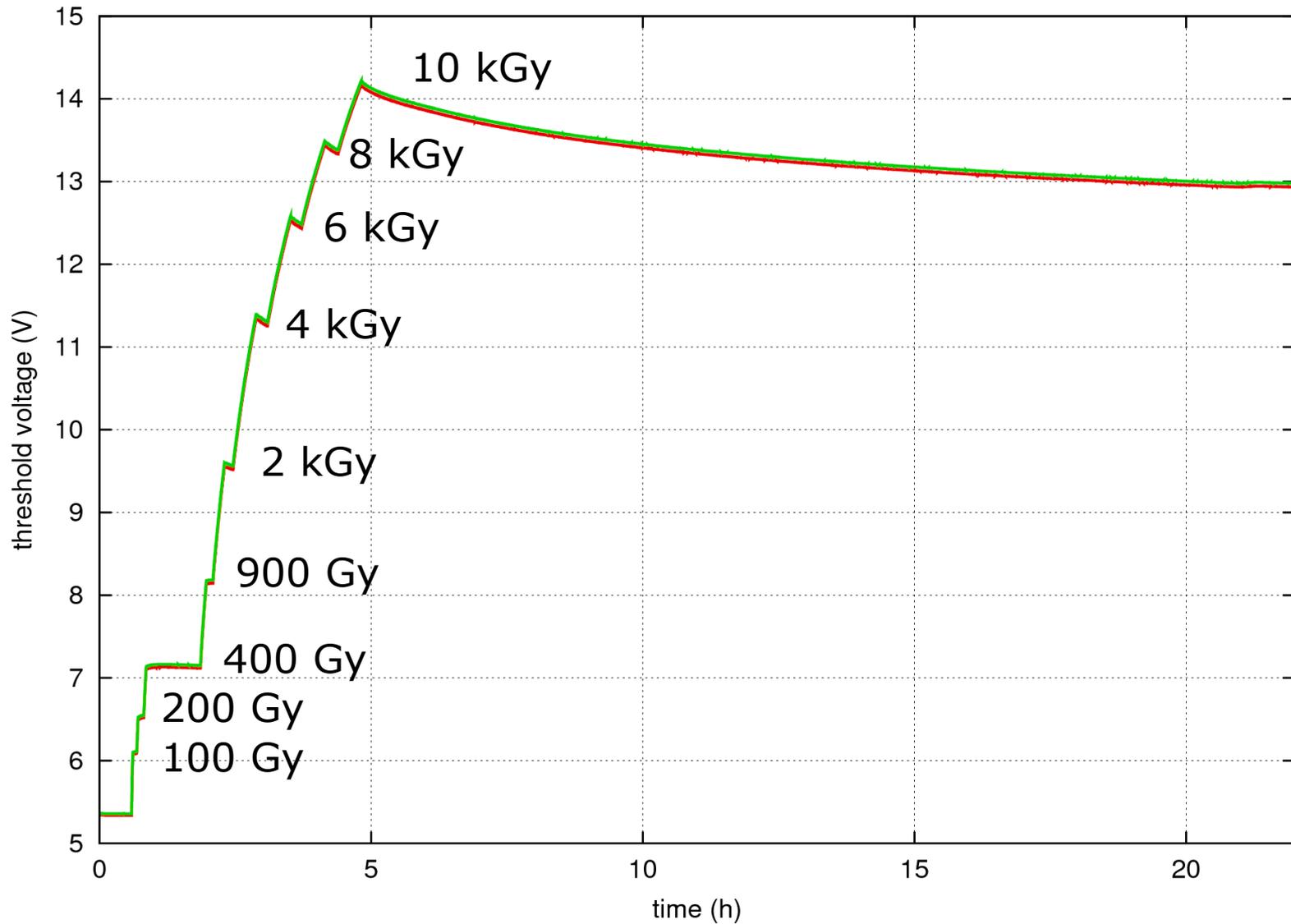


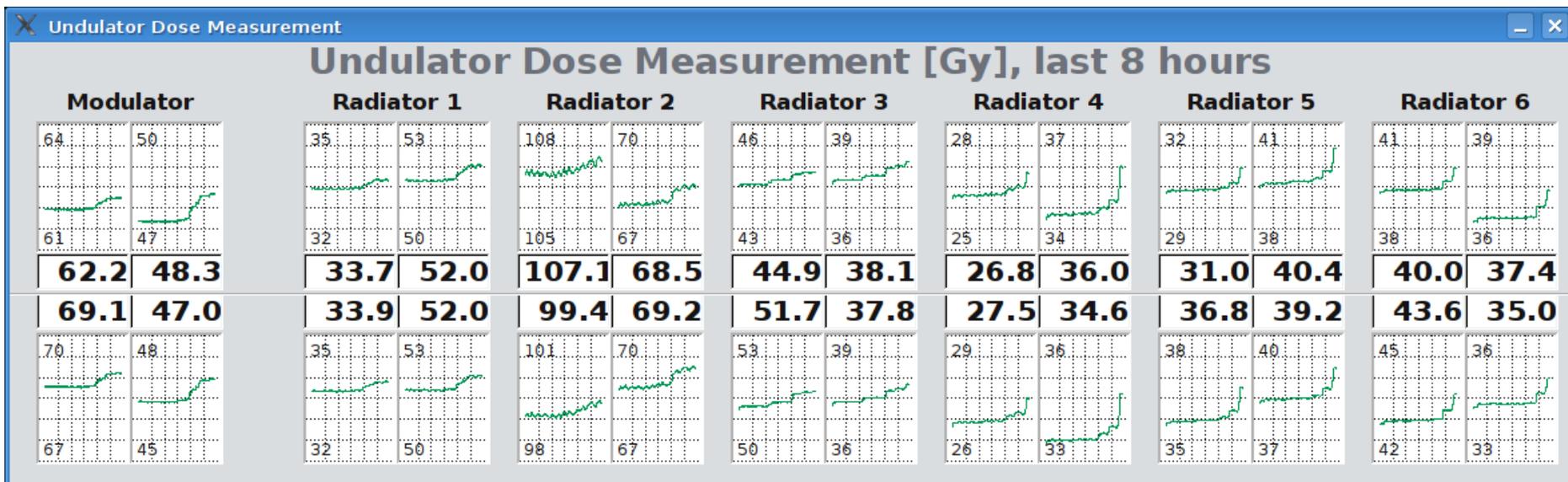


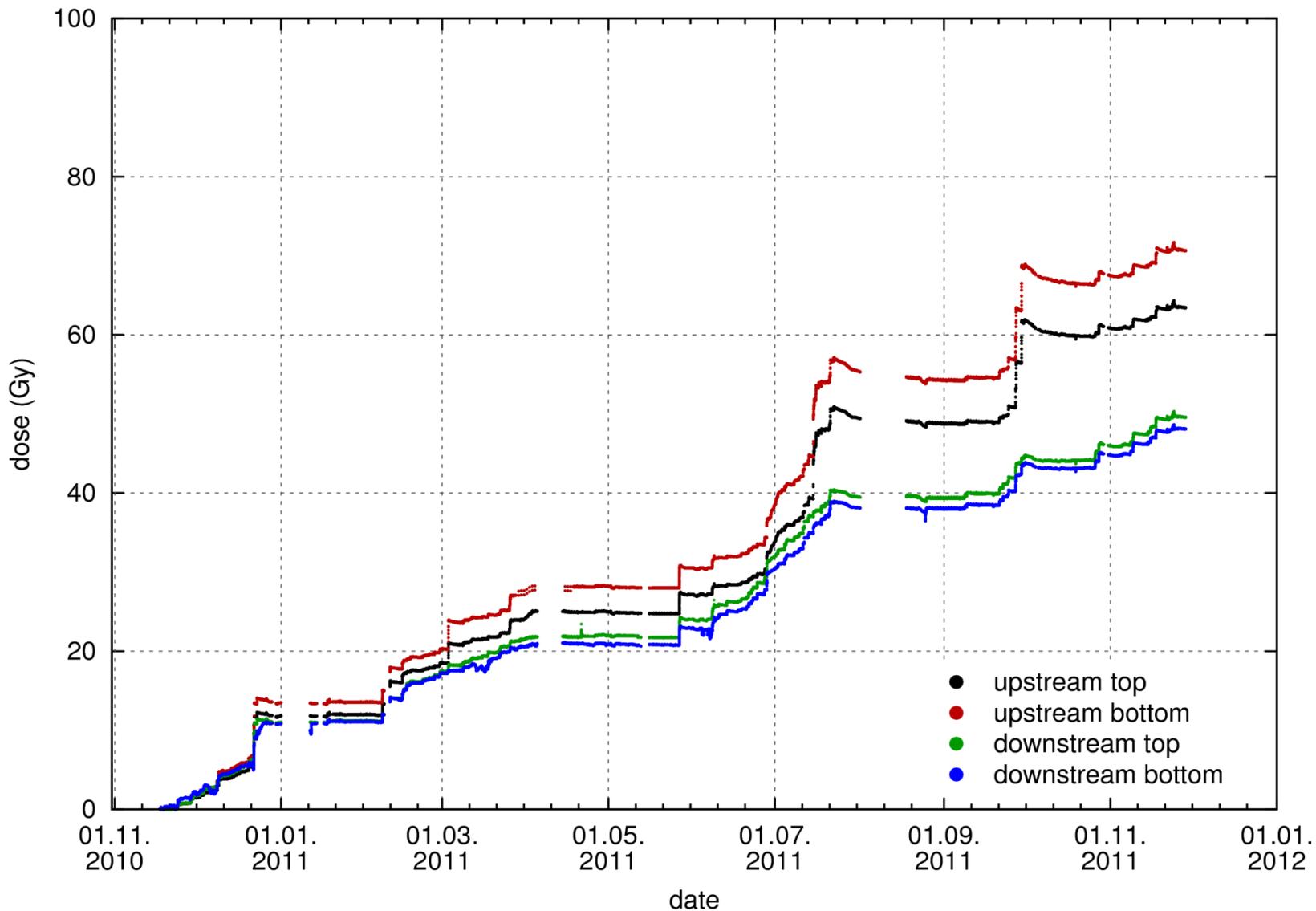
impact of 500 pC bunches at 10 Hz

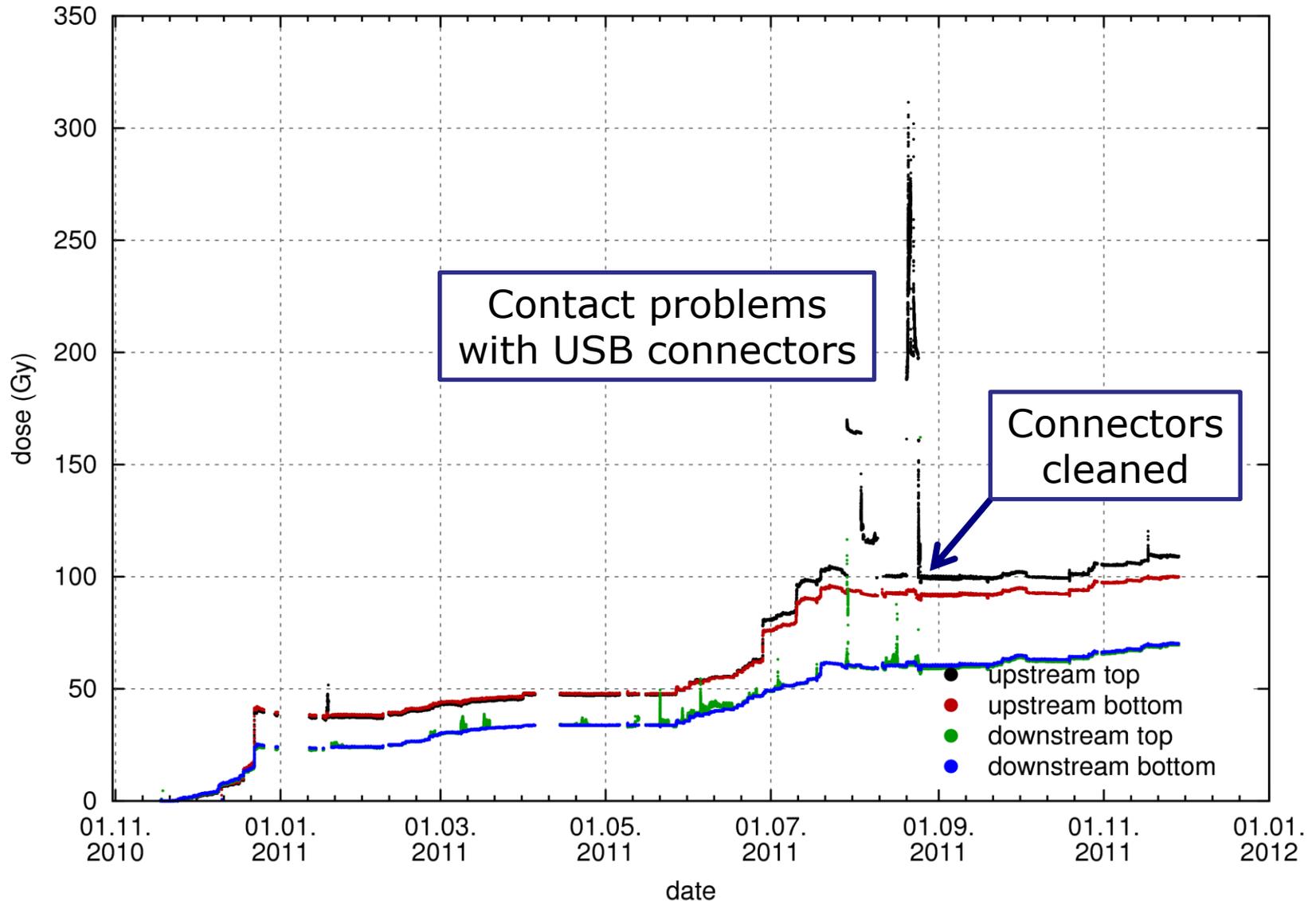


**unpublished  
data**









# Thanks for your interest.

Many thanks to:

- Mario Ferianis, Alessandro Carniel, and the instrumentation and controls groups of Sincrotrone Trieste
- Arne Miller (Risø High Dose Reference Laboratory, DK)
- Andrew Holmes-Siedle (REM Oxford Ltd., UK)